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# Mistakes even the best engineers make

How & why to build better libraries

Natasha Baker, Founder & CEO



# Overview

Why libraries matter

Common symbol & footprint errors

The need for verification

Tools that can help



## In today's talk, you'll learn:

1. Why high-quality libraries matter
2. Common mistakes among a) the newbies and b) the pros
3. Tips & tricks to stay focused on building the best electronics possible!

# Bio

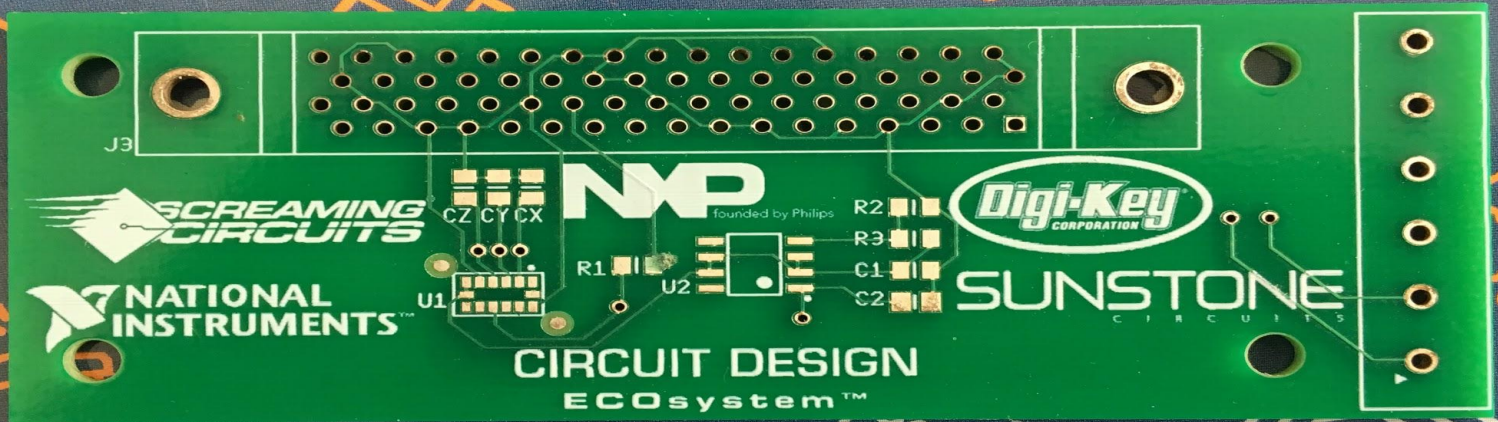


- 12 years working on PCB design tools and libraries
- Electrical & computer engineer from the University of Toronto
- Founder of SnapEDA, electronics library used by 1M engineers

# Why Libraries Matter







**SCREAMING  
CIRCUITS**

**NATIONAL  
INSTRUMENTS™**

CZ CY CX  
U1

**NXP**

Founded by Philips

R1

U2

R2

R3

C1

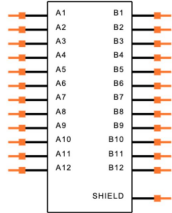
C2

**Digi-Key**  
CORPORATION

**SUNSTONE**  
CIRCUITS

**CIRCUIT DESIGN  
ECOsystem™**

# What is the scope of today's talk?

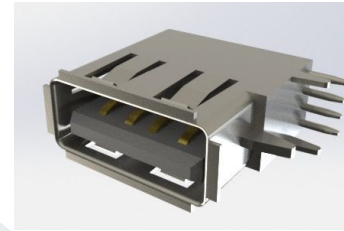
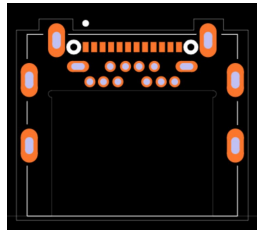


## Schematic Capture & Simulation

Each component requires a **schematic symbol** which describes the pin functions and types. Engineers may also simulate their designs.

## PCB Layout

The **footprint** is used when designing the physical layout of the circuit board. It describes where the component will get soldered onto the board



## Mechanical Design

To see if a PCB will fit within the casing, **3D models** are used to check for clearances, and other factors.



# Why well-defined libraries matter

- 1 Necessary for ensuring proper manufacturing
- 2 To enable other CAD tool features to function properly (ex: ERC)
- 3 Documentation (ensure readability and re-use through consistency)





# Why are libraries so hard to get right?

1

Extremely detail-oriented

2

Lack of datasheet consistency and standards

3

Lack of industry standards or alignment

4

Varying manufacturing capabilities

5

Lack of universal file format

6

Libraries get no glory



# Standards



# The scope is massive



Many details required  
for each pin, pad and  
part

Changing industry  
standards

Company-specific  
standards

**300 Million+  
Electronics  
Components**

Infinite user preferences

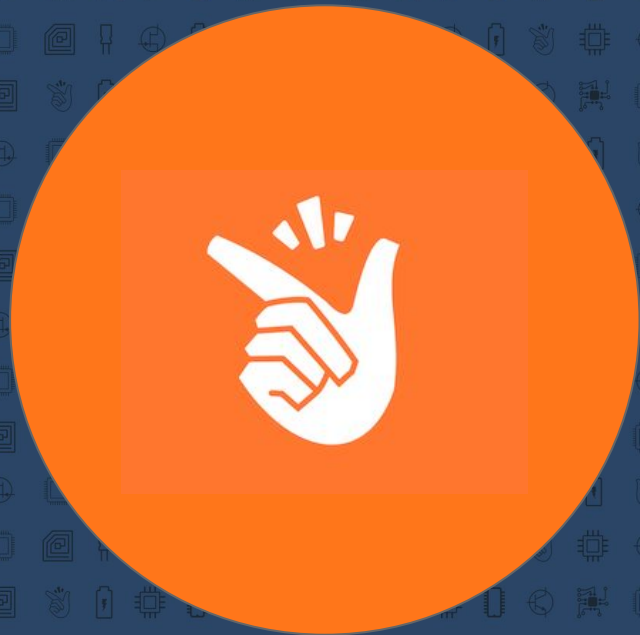
Application-specific  
requirements

Tool-specific quirks



**“Never discuss politics, religion or PCB library standards in polite company.”**

# Library Errors - The Basics

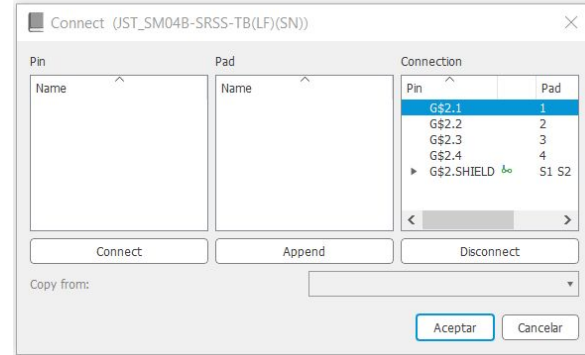
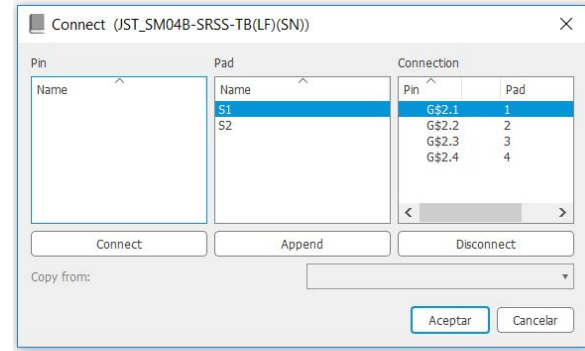
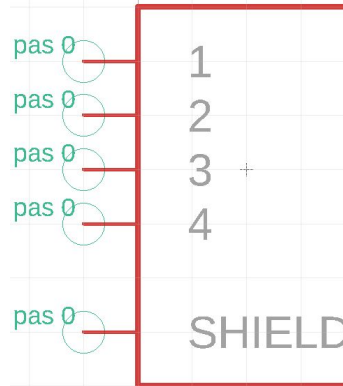
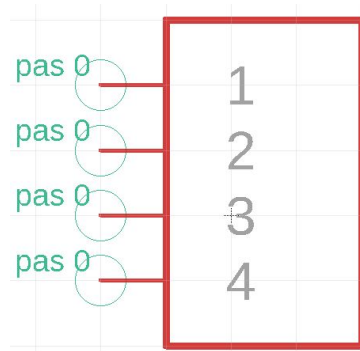




# # 1 Pin mapping issues

Mapping pins to the wrong pads is a critical mistake, causing improperly connected pins, or even worse, creating shorts.

**How to avoid:** Double check all connections.



## #2 Pad dimension errors

If you are manually drawing pad layouts, it is easy to make mistakes.

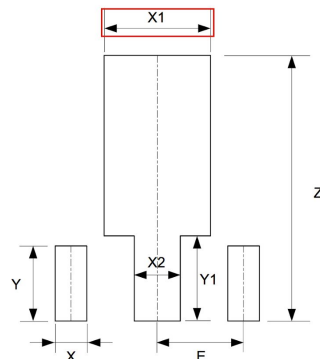
If you get one pad length off by a fraction of a millimeter it can cause soldering issues.



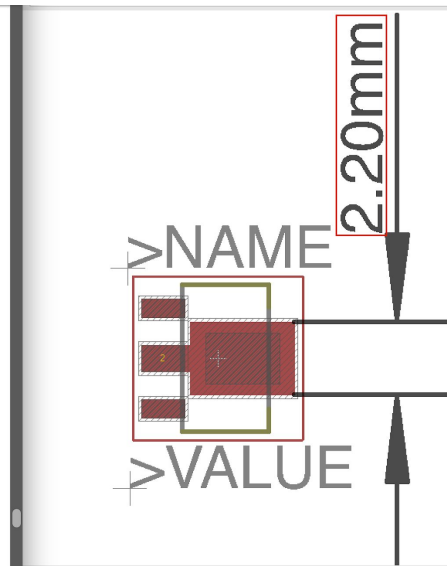
AP2204

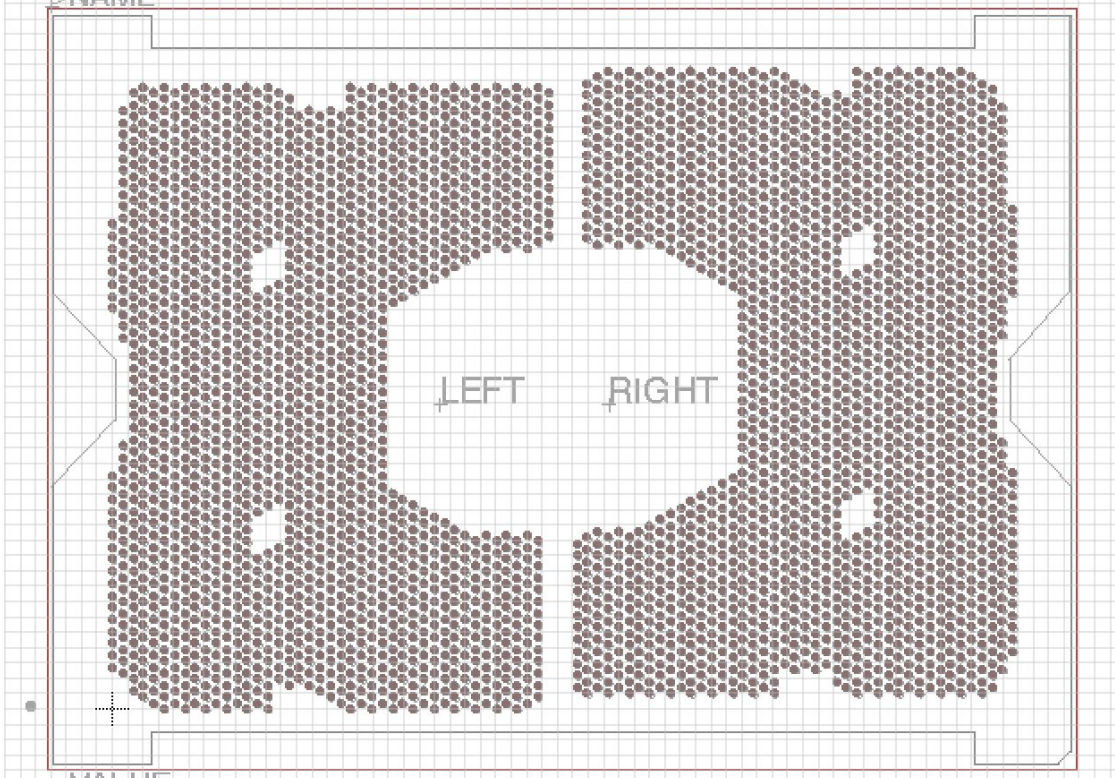
### Suggested Pad Layout (Cont.)

(2) Package Type: SOT-89



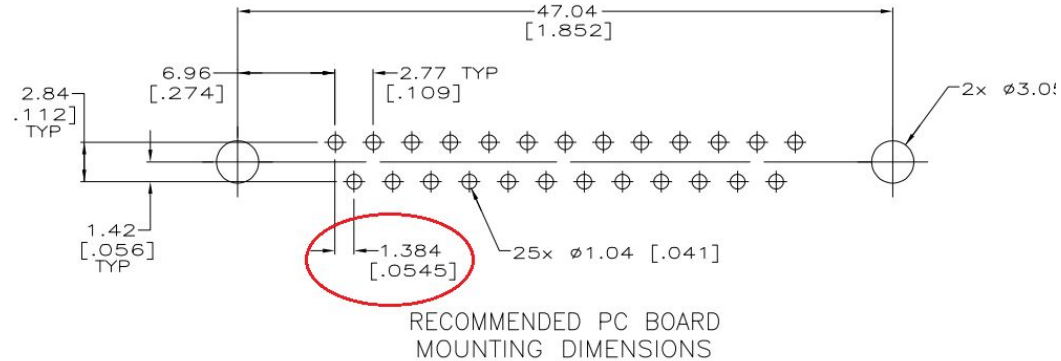
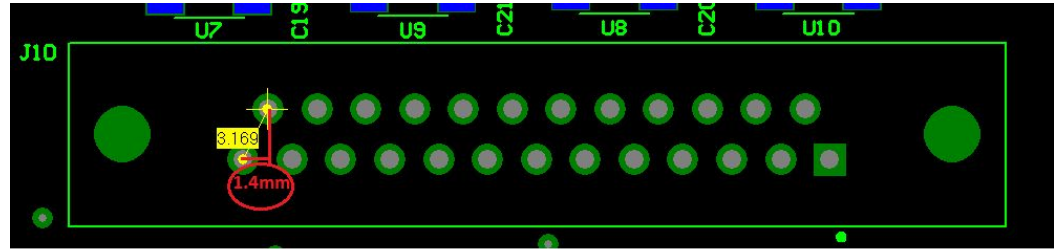
Dimensions	Z (mm)/(inch)	X (mm)/(inch)	X1 (mm)/(inch)	X2 (mm)/(inch)	Y (mm)/(inch)	V1 (mm)/(inch)	E (mm)/(inch)
Value	4.600/0.181	0.550/0.022	1.850/0.073	0.800/0.031	1.300/0.051	1.475/0.058	1.500/0.059





# #3 Rounding dimensions

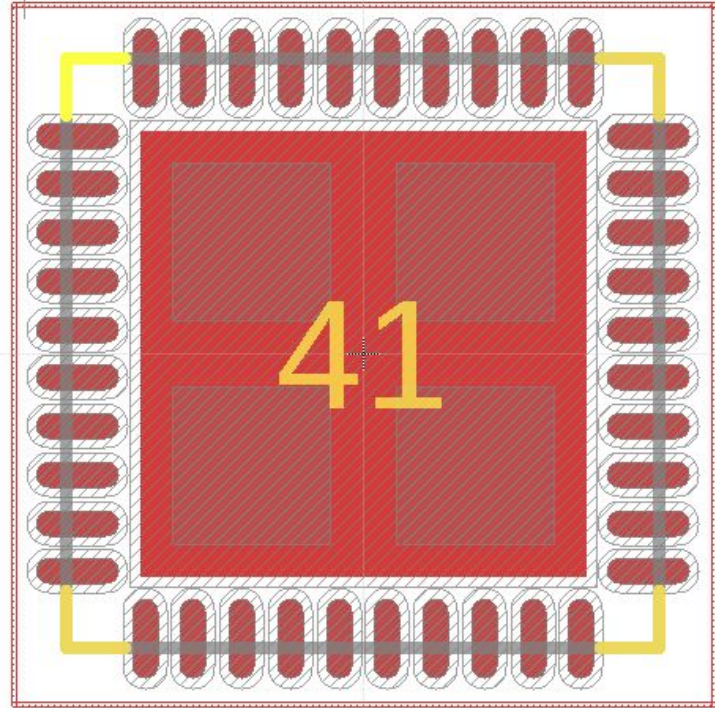
During conversion of metric to imperial units or vice versa, units should never be rounded



## #4 Silkscreen too close to pads

One of the most common issues seen in library design is silkscreen overlapping exposed copper on pads.

If this happens it could inhibit the solder from flowing and will result in a bad joint.

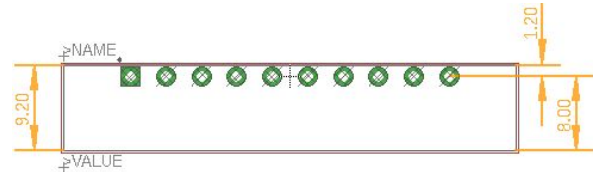
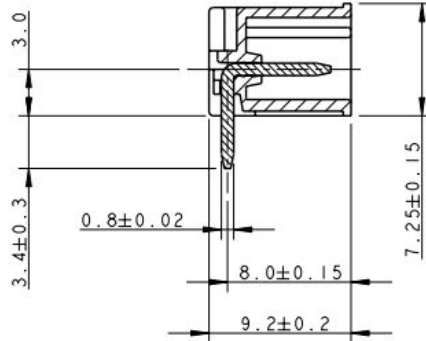
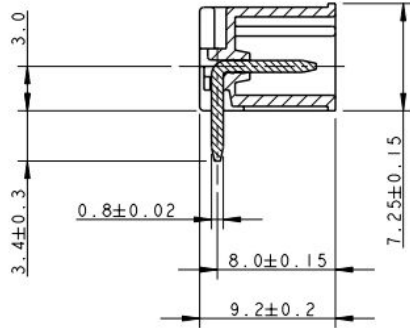




## #4 Wrong outline dimensions

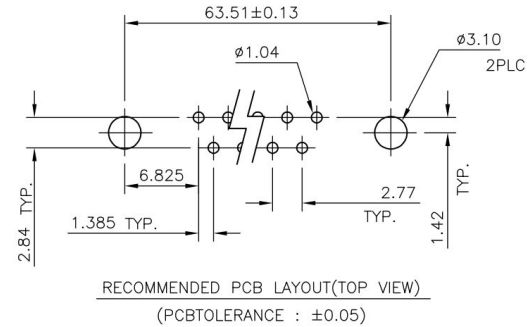
Wrong component outline and courtyard dimensions will cause overlapping of nearby components in the PCB and could produce critical manufacturing issues.

Confusing component outline dimensions may result in trying to fit a RA header on a vertical header footprint, or vice versa.

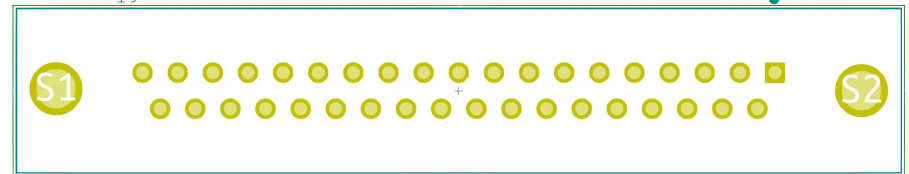


## #5 Wrong pin sequence

Some connectors are numbered from top to bottom, others are numbered from left to right. If the pin numbering of your footprint is incorrect you'll have wrong connections.



TE\_3-1634221-2  
19



VAL\*\* 37

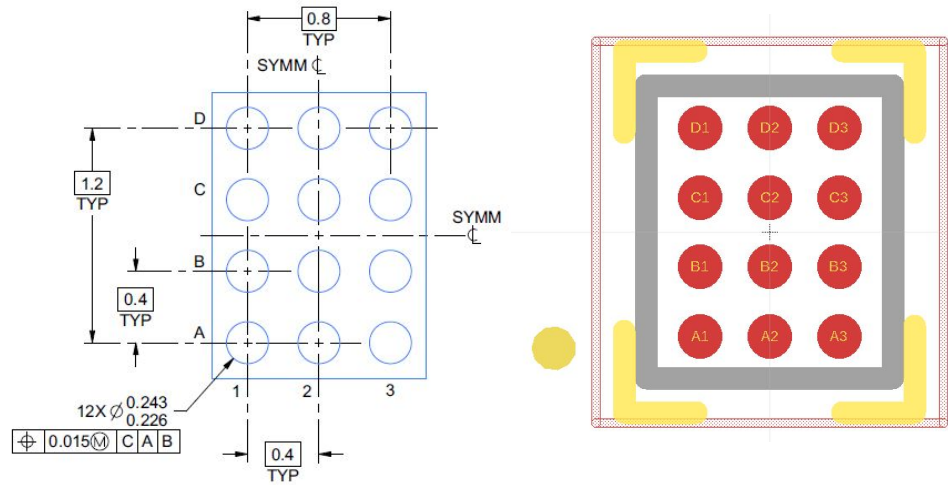
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# Library Errors - The Ones Even Pros Miss



# #1 Mirrored views

This occurs when the top view of a part is mistaken for the bottom view. Generally, component vendors draw based on the top view. But occasionally, they'll do the opposite.



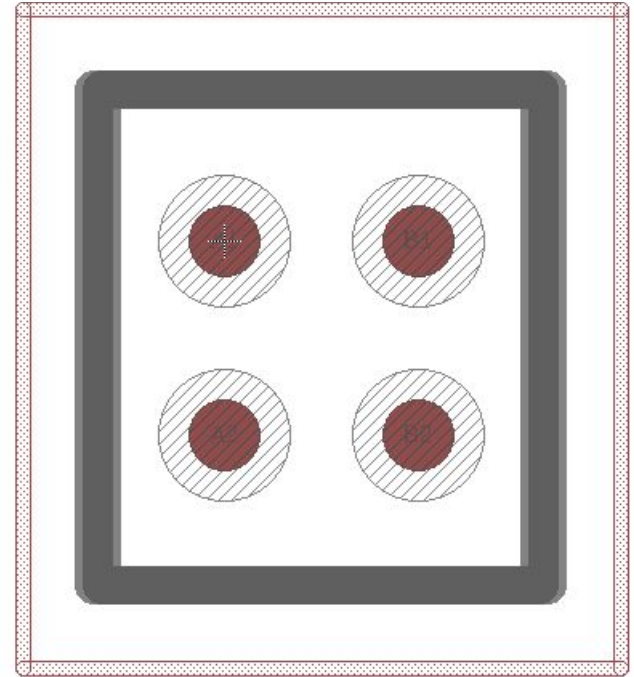




## #3 Wrong centroid

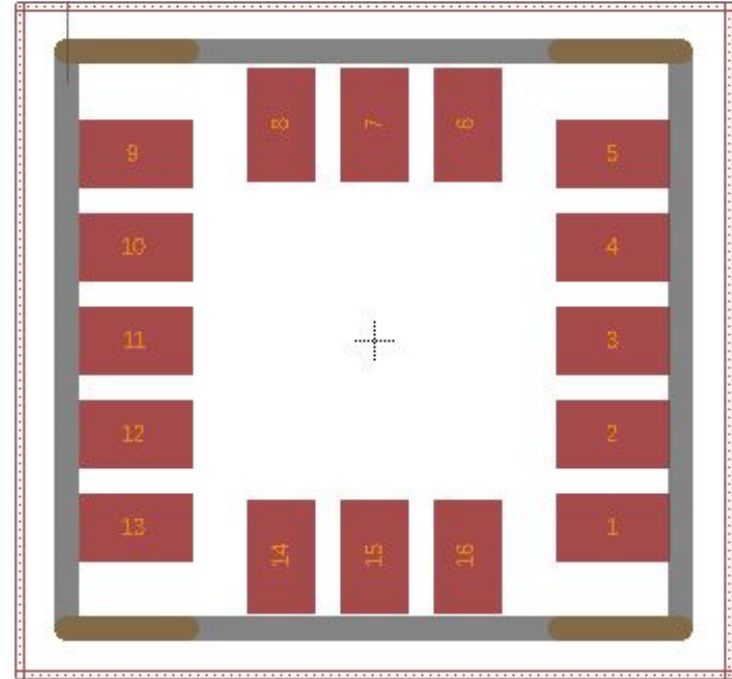
The center-of-mass of a part is defined by an X-Y location and this concept is known as the part centroid.

If your centroid coordinates are off then the pick-and-place machine will try to pick components from a location that may not stick well to the package.



## #4 Wrong component zero orientation

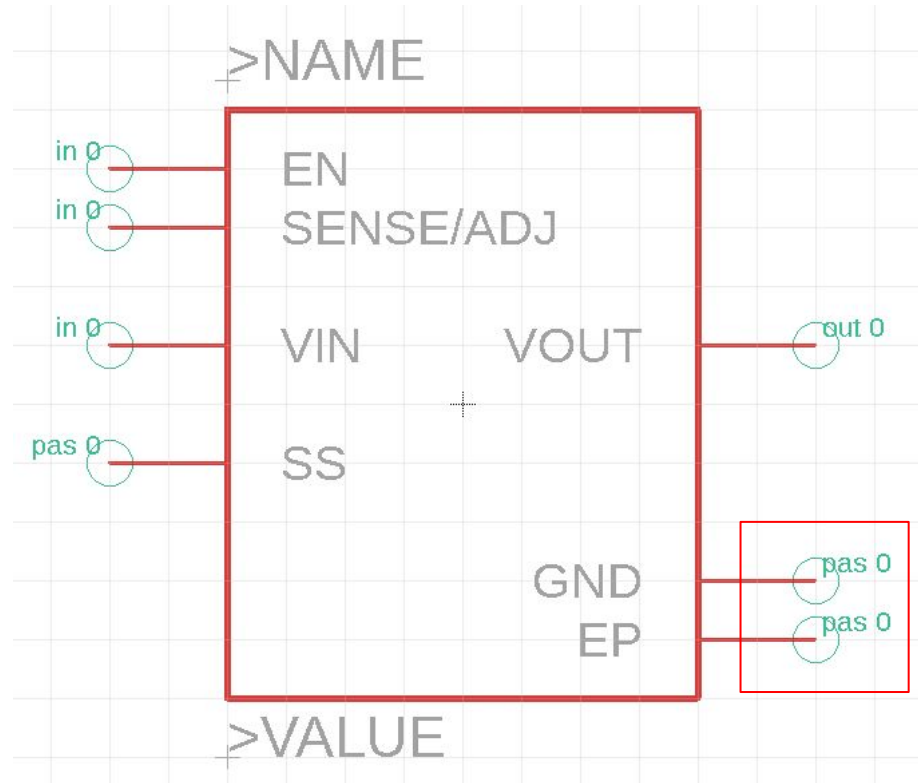
The zero component orientations expressed in IPC-7351 are defined for the description of electronic component orientations. They're important for the pick-and-place to figure out how to place the component during assembly



## #5 Improper pin definitions

To define the logical direction of signal flow in a schematic symbol, you need to understand the function of the component you are creating.

If pins are not defined properly ERC checks will not work .





## #7 Not breaking up solder paste in thermal pads

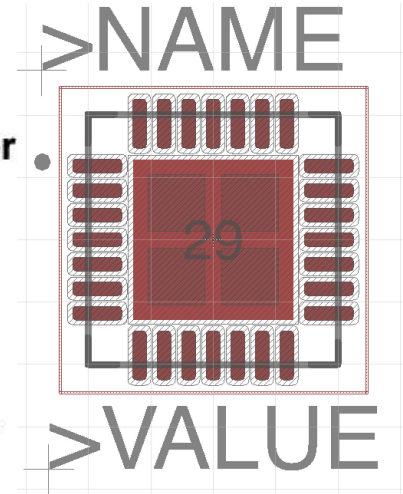
This can cause float where the part is too high and doesn't connect to pins.



QFN mounted with too much solder in center pad area



QFN mounted with reduced solder paste in center pad area





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**Question: Do different assembly shops handle footprints differently?**

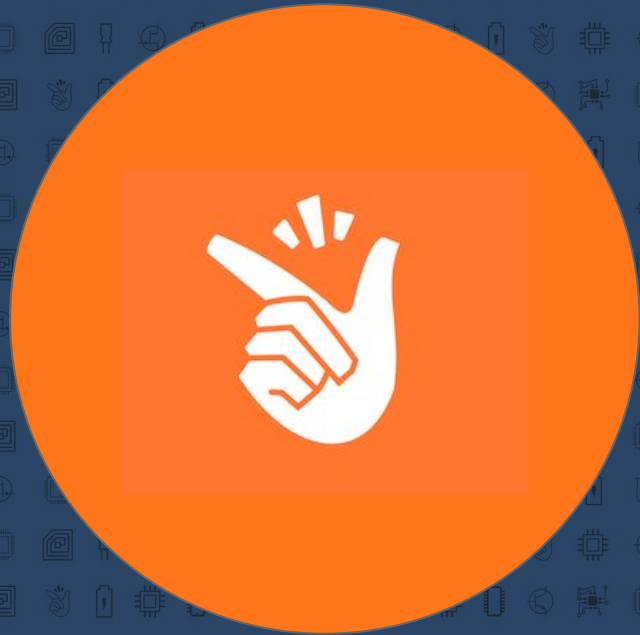


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# Question: Do different assembly houses require different footprints?



# Checklists & Verification

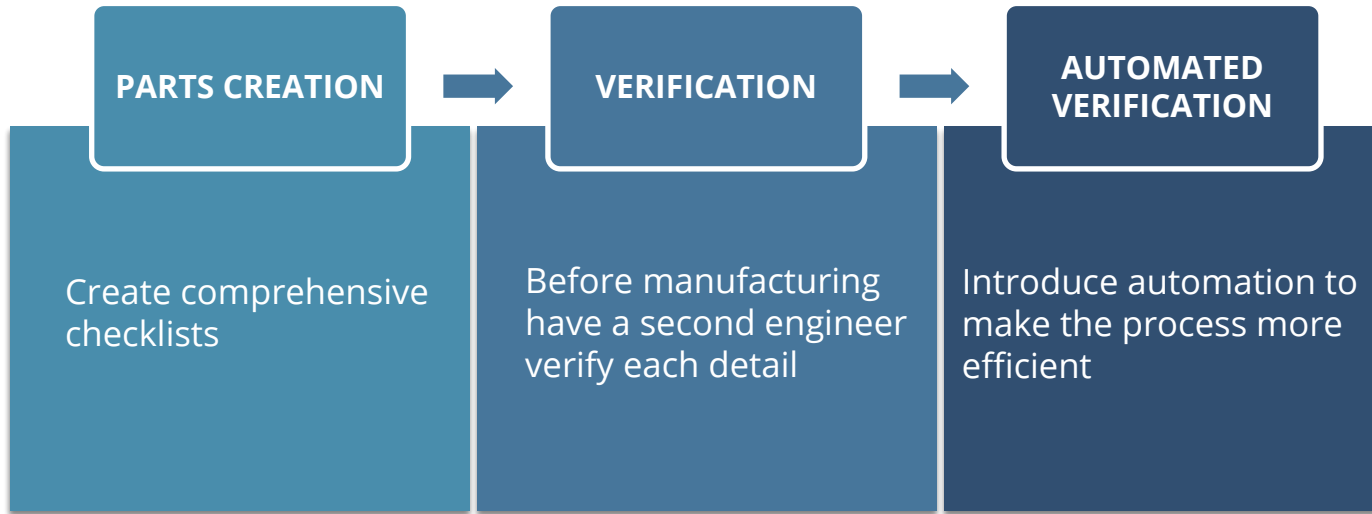




# The need to verify libraries

- Regardless of whether you got a library from the web, component vendor website, or made it yourself, it always needs to go through a thorough verification process

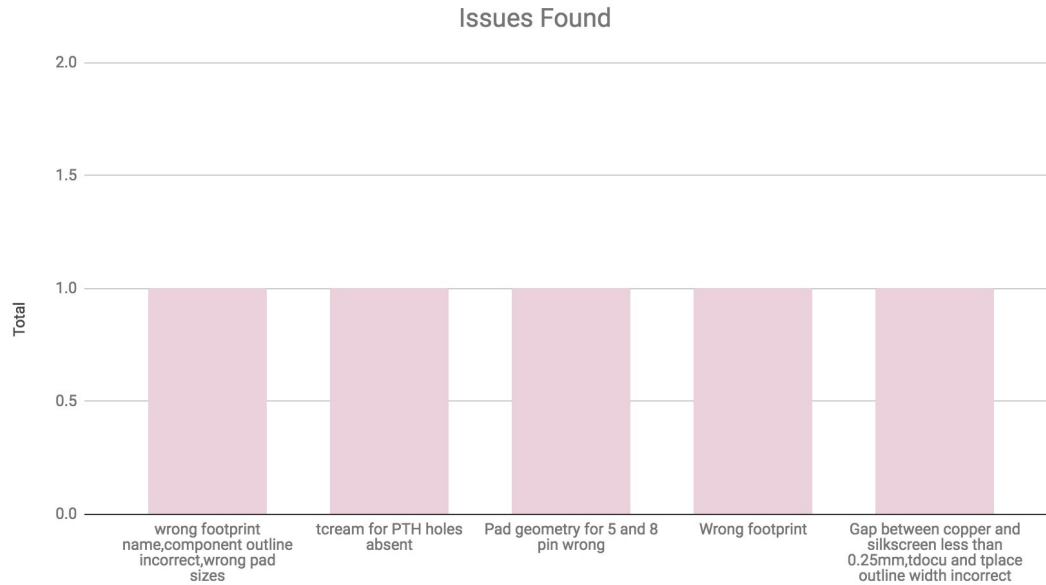
# Step 1: Define the process



## Step 2: Create, maintain and enforce checklists

- Package name should follow IPC naming convention
- Follow IPC Zero orientation with pin 1 upper left
- Ensure that the pin mapping is the top view of the chip and not a mirrored view from the bottom.
- Ensure the spacing between silkscreen and copper is at least  $0.25\text{mm} + 0.0635 (\text{line width} / 2) = 0.32$
- Body outlines or any part of the footprint created with the tPlace layer should not collide/overlap with the pads.
- Add a body outline (0.127 mm lead width) in tDocu and tPlace layer
- Exposed pad's tCream layer (paste) should be 40%-50% of the area of the exposed pad
- Add a tKeepout outline with 0.05mm lead width enclosing the footprint (0.25mm away from the pads/component outline)
- Irregular-shapes pads (including tcream, tstop, tkeepout) created with polygon tool, lead width should be 0.001 mm (not zero)
- For components with cut-outs, draw the cut-out in Milling layer using line width 0 mm

## Step 3: Measure, learn & iterate





## Step 4: Automate

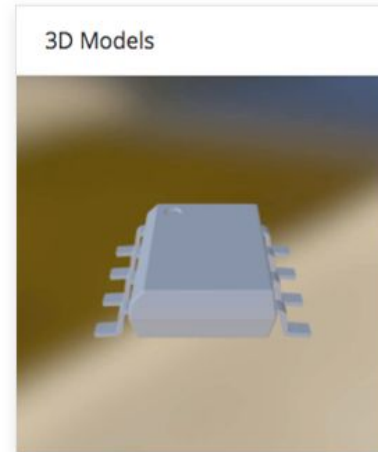
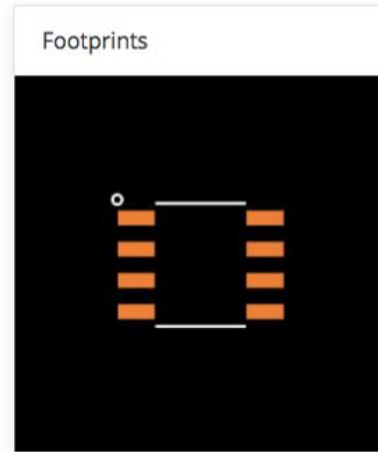
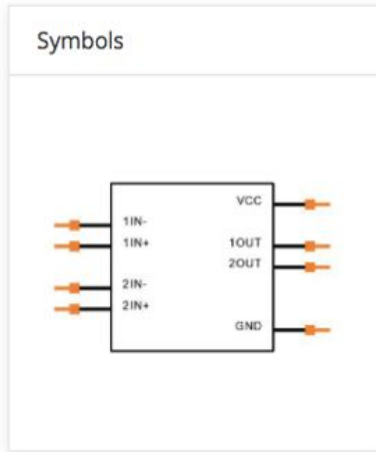
- To prevent human error, and minimize library efforts, automation is your friend!
- What parts of the creation and verification processes can you automate?



**What tools  
are available  
to help?**



- Symbols, footprints, and 3D models for millions of electronics components



- Create schematic symbols using simple computer vision and OCR in minutes

1

MAX1649/MAX16

PIN	NAME	
1	OUT	Sense Input for fixed 5V or 3.3V output operation. Although it is connected to the output of the circuit, it is not adjustable-output operation.
2	FB	Feedback Input. Connect to GND for fixed-output operation. Connect to the feedback network for adjustable-output operation. See Settling Time for details.
3	SHDN	Active-High Shutdown Input. Part is placed in standby mode when this input is high. In standby mode, output, and external MOSFET are turned off.
4	REF	1.5V Reference Output that can source 100µA.
5	V+	Positive Power-Supply Input
6	CS	Current-Sense Input. Connect current-sense resistor to this input. When the current-sense resistor equals the current-limit trip level, the external MOSFET is turned off.
7	EXT	Gate Drive for External P-Channel MOSFET. EXT is connected to the gate of the external MOSFET.
8	GND	Ground

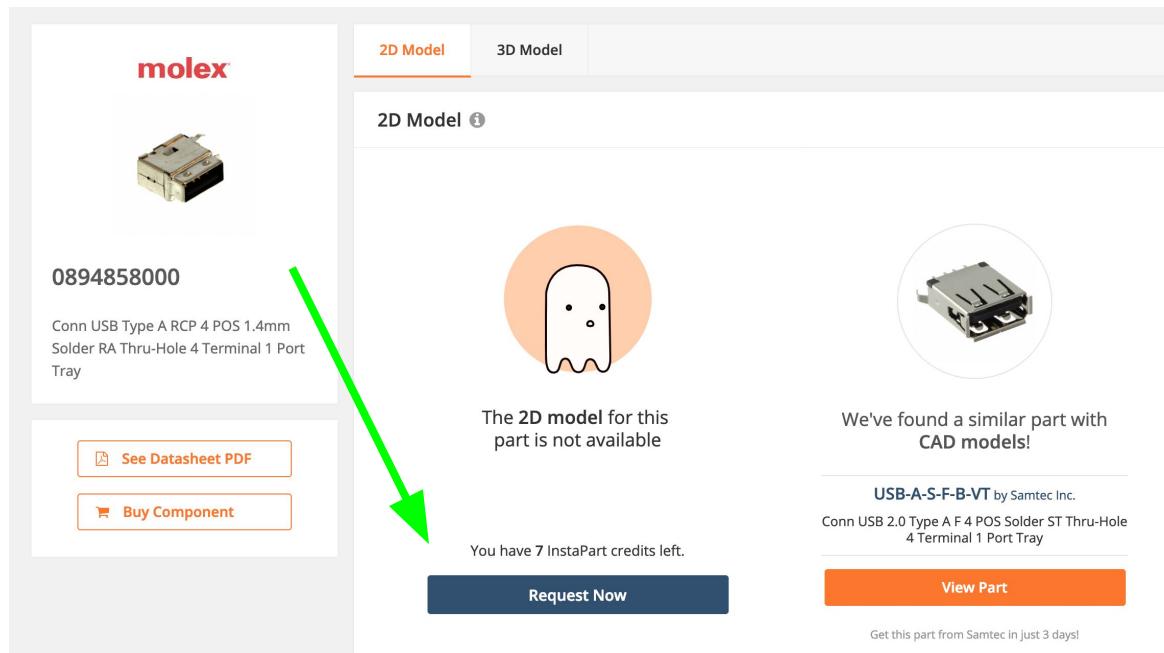
2

	Remove	Remove	
	Pin Names and Numbers		Pin Types
X	1	OUT	Auto ▼
X	2	FB	Auto ▼
X	3	SHDN	Auto ▼
X	4	REF	Auto ▼
X	5	V+	Auto ▼
X	6	CS	Auto ▼
X	7	EXT	Auto ▼
X	8	GND	
+			


3

The screenshot shows the InstaBuild web interface. On the left, the 'Symbol' tab displays a schematic symbol for the MAX1651ESA+ component with pins labeled CS, SHDN, V+, EXT, FB, OUT, REF, and GND. On the right, the 'Footprint' tab shows a top-down view of the component's footprint with orange pads. Below the symbol and footprint, there are dropdown menus for the component name (MAX1651ESA+ and SOIC127P600X175-BN) and buttons for 'Download Symbol and Footprint' and 'Download Footprint'.

- Request any symbol & footprint and get it in 24h



**molex**



**0894858000**


Conn USB Type A RCP 4 POS 1.4mm  
Solder RA Thru-Hole 4 Terminal 1 Port  
Tray

[See Datasheet PDF](#)

[Buy Component](#)

**2D Model** | 3D Model


**2D Model** ⓘ



The 2D model for this part is not available

You have 7 InstaPart credits left.

[Request Now](#)



We've found a similar part with CAD models!

**USB-A-S-F-B-VT** by Samtec Inc.  
Conn USB 2.0 Type A F 4 POS Solder ST Thru-Hole  
4 Terminal 1 Port Tray

[View Part](#)

Get this part from Samtec in just 3 days!

- Validate libraries in real-time



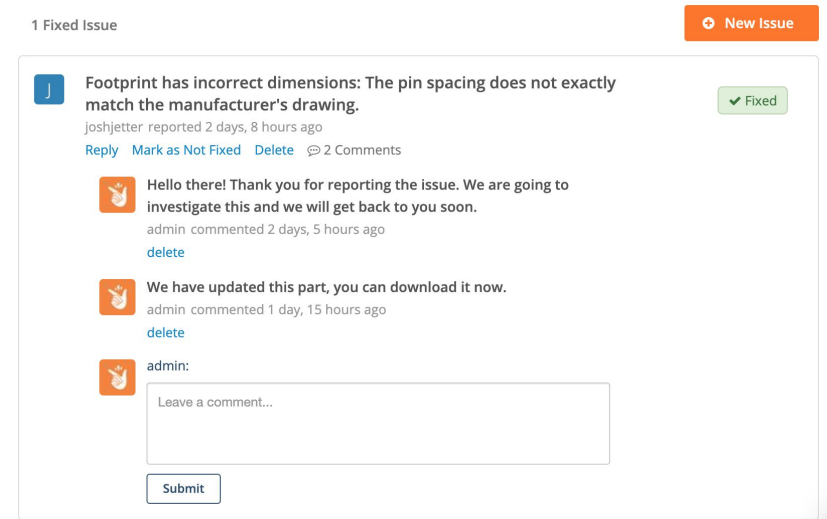
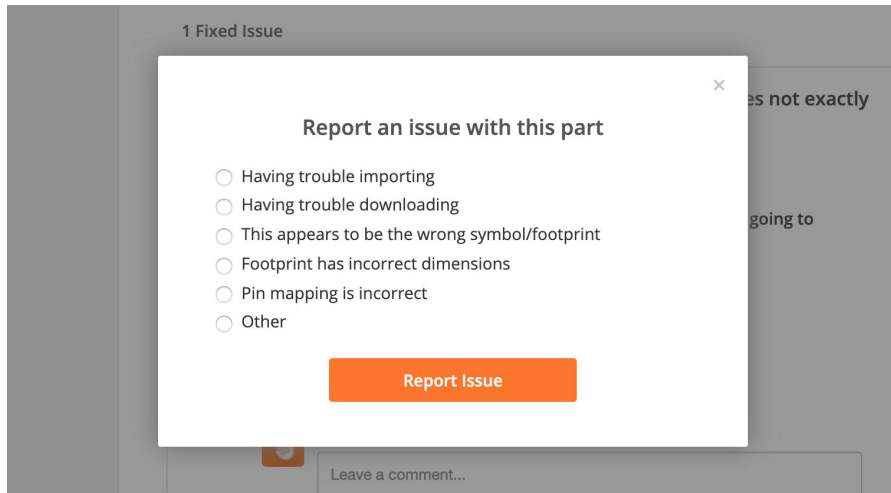
### Verification Checker Beta [i](#)

This report for the MT46V32M16BN-5B:F was generated by our patent-pending Verification Checker. It checks for common manufacturability issues to ensure quality.

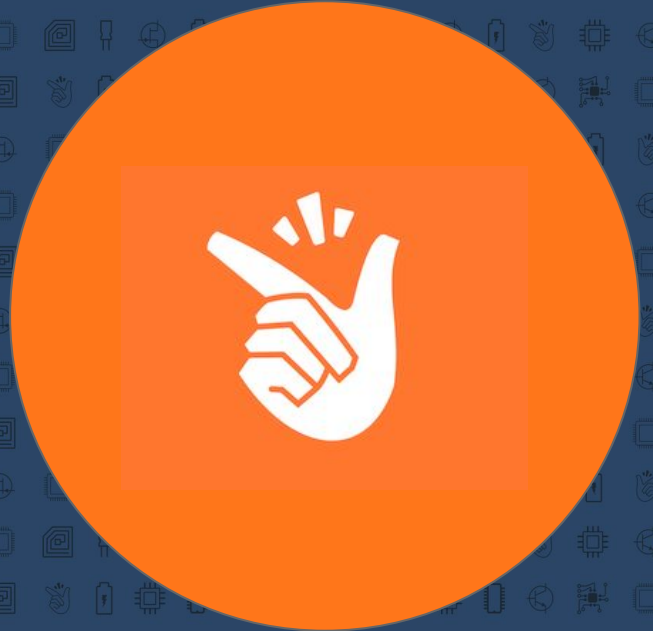
Legend: ✓ Pass ! Please Inspect ✗ Fail

<span style="color: green;">✓</span> <b>Manufacturability</b>	Checks that identify issues related to manufacturability	<span>⊖</span>
<span style="color: green;">✓</span>	Silkscreen object should not overlap pads	
<span style="color: green;">✓</span>	Footprint (FBGA60-8X20) should be centered at (0, 0) and is at (0, 0)	
<span style="color: green;">✓</span>	Surface mount pads should be on the top layer	
<span style="color: green;">✓</span> <b>Documentation</b>	Ensuring that schematic and board layout have good documentation	<span>⊖</span>
<span style="color: green;">✓</span>	Package FBGA60-8X20 should have the text 'NAME' for the layer name text.	
<span style="color: green;">✓</span>	Package FBGA60-8X20 should have the text 'VALUE' for the layer value text.	
<span style="color: green;">✓</span>	Text should be on the documentation layer	
<span style="color: orange;">!</span> <b>Miscellaneous</b>	Miscellaneous checks	<span>⊖</span>
<span style="color: orange;">!</span>	Package name FBGA60-8X20 should be an IPC name	

- Share and learn from the engineering community



# Summary





# Summary

- 1 Libraries are necessary for reliable manufacturing, readability, and ERC
- 2 Implementing verification checklists and processes is essential
- 3 Other tools can help increase the efficiency and productivity



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# Thanks to SnapEDA's Component Engineering Team!



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# Questions?

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